



SDI Review Form 1.6

Journal Name:	Physical Science International Journal
Manuscript Number:	Ms_PSIJ_29024
Title of the Manuscript:	Influence of Annealing Temperature on the Physical Properties of Polycrystalline Cu ₂ SnSe ₃ Thin Films Prepared by Thermal Vacuum Evaporation Technique
Type of the Article	Original Research Article

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This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound.

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PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments	<p>Experimental</p> <p>Paragraph 1 line 2 delete the second point.</p> <p>Paragraph 1 line 4 the I-V characteristic of the films has been investigated by using the Van der Pauw method or by Keithley 2700 Multimeter/Data Acquisition System??</p> <p>3.1 Scanning Electron Microscopy (SEM)</p> <p>Paragraph 1 line 4 delete colon in mechanical properties and rewrite this line ... mechanical, properties, etc. of Cu₂SnSe₃ thin films with is surface morphology.</p> <p>Paragraph 1 line 4 to 6 Delete... Morphological investigations were carried out on six samples of Cu₂SnSe₃ thin films annealed at different temperatures using scanning electron microscope (SEM). Because the last paragraph corresponds to experimental procedure</p> <p>Paragraph 1 line 6 To change times by x. Paragraph 1 line 7 delete... in Figures 1 and 2, almost</p>	<p>Line 2 removed - The wide range of magnification makes it suitable for investigation of microstructure of Cu₂SnSe₃ thin films. The authors using Van der pauw techniques which explained earlier in chapter 2. Experimental. Keithley 2700 Multimeter/Data Acquisition System is only the tools.</p> <p>Paragraph were rephrase to "the electrical behaviour, crystallinity, mechanical properties, etc. of Cu₂SnSe₃ thin films with is surface morphology."</p> <p>Authors agreed that there is no issue with this statement and we try to remains the sentence without delete it right away.</p> <p>Times changed to x</p> <p>The sentence will be kept remains</p> <p>Micro cracks can be seen clearly in Figure 3(i). Please refer to the Figure 3.</p> <p>Changed to Figure 3. Definitely addressed earlier the possibilities for the peaks changes were compared to the</p>



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	<p>finish.</p> <p>Results</p> <p>3.1 Paragraph 3 line 3 the authors must show the micro cracks to 400 and 500 C. Because in the images these seem needles and elongated particles as fibers.</p> <p>3.2 Paragraph 1 line 6, review if the information corresponds to figure 3 or table No.1 <i>Figure 5.26?</i>. For figure 3 to include the results of the EDS in the spectrum (quantification as shows the system), because in the figure No.3, it not possible to observe as peaks decrease when the temperature increases.</p> <p>The thin films were obtained by Thermal Vacuum Evaporation Technique, however are low references about this technique, the authors compared their results with other techniques and they affirm that "well known that morphology of semiconductor thin films are influenced by the method of synthesis and the annealing temperature employed"</p> <p>According to the results in the table No.1 when the temperature increases the copper decreases, but, from being deposited, the material does not have the stoichiometric ratio. It is recommended to verify and include the composition of the starting material before evaporation</p> <p>Delete figure 4 and 5 are not necessities. After ec. 4, line 2, delete conductivity. Delete one, table No.2 or figure 7, they content the same information.</p> <p>Conclusions Delete deposition technique, because the authors did</p>	<p>Scanning Electron Microscopes images. Well said. Thank you for the comments.</p> <p>Thank you for reviewer suggestions. Authors will take it into account for other future works on similar thin films as suggested. Authors try to maintain the entire figure to provide better picture for the journal reader about the research done with the thin films.</p> <p>We try to provide all the information about the deposited thin films and comparison can be understood better with this kind of result. Hopefully this is will be not deleted. The EDX analysis revealed that the as-deposited and annealed thin films of Cu_2SnSe_3 are found to contain the nearly stoichiometric composition calculated earlier where atomic percentage for each element Cu, Sn, and Se corresponding to 26%, 25%, and 49%. However, yes we agreed and already mentioned that the composition comes with ratio (2:1:3) which is is 33.33, 16.67 and 50%.</p>
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	<p>not have two process or more to compare. Cu₂SnSe₃ films show a strong dependence on the film deposition technique.</p> <p>The atomic stoichiometric ratio for Cu₂SnSe₃ is 33.33, 16.67 and 50 approx. respectively. And neither thin film has the same.</p>	
<u>Minor</u> REVISION comments		
<u>Optional/General</u> comments		